PRODUCT / PROCESS CHANGE INFORMATION

1. PCI basic data

1.1 Company	STMicroelectronics International N.V
1.2 PCI No.	AMS/20/12455
1.3 Title of PCI	Optimization of TEG structures positioning in scribe lines of asic die of LSM6DSO32TR, LSM6DSTQTR, LSM6DSTTR.
1.4 Product Category	See Products List
1.5 Issue date	2020-11-16

2. PCI Team

2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Andrea Mario ONETTI
2.1.2 Marketing Manager	Simone FERRI
2.1.3 Quality Manager	Michele CALDERONI

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Wafer Fab (Process)	Mask Frame : introduction of new structure or never tested structure, change of die scribe separation or scribe line width	ST FRANCE

4. Description of change

	Old	New
4.1 Description	-Actual TEG layout in scribe lines -Actual die area	-New rearranged TEG layout in scribe lines -No impact on die area
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	No Impact	

5. Reason / motivation for change

5.1 Motivation	The implementation of the change guarantees the continuous improvement in assy process.
5.2 Customer Benefit	QUALITY IMPROVEMENT

6. Marking of parts / traceability of change

6.1 Description	by code

7. Timing / schedule

7.1 Date of qualification results	2021-01-11
7.2 Intended start of delivery	2021-01-18
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description			
8.2 Qualification report and qualification results	In progress	**Issue Date**	

9. Attachments (additional documentations)

12455 Public product.pdf

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	LSM6DSO32TR	

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Public Products List

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PCI Title : Optimization of TEG structures positioning in scribe lines of asic die of LSM6DSO32TR, LSM6DSTQTR, LSM6DSTTR.
PCI Reference : AMS/20/12455

Subject : Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

LSM6DSO32TR		

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